

P-Channel Power MOSFET

-30V, -34A, 8.5mΩ

FEATURES

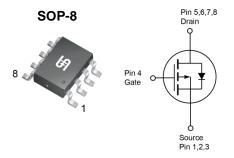
- Low R_{DS(ON)} to minimize conductive losses
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

ΛD	DI	IC	ΔΤΙ	PI

- DC-DC Converters
- Battery Power Management
- Load Switch
- BLDC Motor Drives

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V _{DS}		-30	V	
R _{DS(on)} (max)	V _{GS} = -10V	8.5		
	$V_{GS} = -4.5V$	14	mΩ	
Q_g		28	nC	





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

PARAMETER Drain-Source Voltage		SYMBOL	LIMIT	UNIT	
		V_{DS}	-30	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current (Note 1)	$T_C = 25^{\circ}C$	1	-34		
Continuous Drain Current	$T_A = 25^{\circ}C$	I _D	-13	A	
Pulsed Drain Current		I _{DM}	-136	Α	
Single Pulse Avalanche Current (Note 2)		I _{AS}	-23	А	
Single Pulse Avalanche Energy (Note 2)		E _{AS}	79	mJ	
Tetal Davis Disain etian	T _C = 25°C		14	107	
Total Power Dissipation	T _C = 125°C	P _D	2.8	W	
Total Davier Dissination	T _A = 25°C	Б	2.2	10/	
Total Power Dissipation	T _A = 125°C	P _D	0.4	W	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	- 55 to +150	°C	

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction to Case Thermal Resistance	R _{eJC}	9	°C/W		
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	57	°C/W		

Thermal Performance Note: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JA}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design.

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ELECTRICAL SPECIFICA	FIONS (T _A = 25°C unles	s otherwise no	oted)			
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV _{DSS}	-30			V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	V _{GS(TH)}	-1.2	-1.5	-2.5	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
	$V_{GS} = 0V, V_{DS} = -30V$	I _{DSS}		-1		
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = -30V$ $T_{J} = 125^{\circ}C$				-100	μΑ
Drain-Source On-State Resistance	$V_{GS} = -10V, I_D = -13A$	_		7.7	8.5	mΩ
(Note 3)	$V_{GS} = -4.5V, I_{D} = -10A$	$R_{DS(on)}$		11	14	
Forward Transconductance (Note 3)	$V_{DS} = -5V, I_{D} = -13A$	g _{fs}		35		S
Dynamic (Note 4)						
Total Gate Charge	$V_{GS} = -10V,$ $V_{DS} = -15V, I_{D} = -13A$	Q_g		56		
Total Gate Charge	, 5	Q_g		28		nC
Gate-Source Charge	$V_{GS} = -4.5V$,	Q_{gs}		9		1
Gate-Drain Charge	$V_{DS} = -15V, I_{D} = -10A$	Q_{gd}		11		1
Input Capacitance		C _{iss}		3216		
Output Capacitance	$V_{GS} = 0V, V_{DS} = -15V$	C _{oss}		409		pF
Reverse Transfer Capacitance	f = 1.0MHz	C _{rss}		277		1
Gate Resistance	f = 1.0MHz	R_g	1.8	6	12	Ω
Switching (Note 4)					l	•
Turn-On Delay Time		t _{d(on)}		7.2		
Turn-On Rise Time	$V_{GS} = -10V, V_{DS} = -15V,$	t _r		2.6		
Turn-Off Delay Time	$I_D = -13A$, $R_G = 2\Omega$	t _{d(off)}		68		ns
Turn-Off Fall Time		t _f		33		
Source-Drain Diode						
Forward Voltage (Note 3)	$V_{GS} = 0V, I_{S} = -13A$	V_{SD}			-1	V
Reverse Recovery Time	I _S = -13A ,	t _{rr}		34		ns
Reverse Recovery Charge	dl/dt = 100A/µs	Q_{rr}		19		nC

Notes:

- 1. Silicon limited current only.
- 2. L = 0.3mH, $V_{GS} = -10$ V, $V_{DD} = -25$ V, $R_G = 25\Omega$, $I_{AS} = -23$ A, Starting $T_J = 25$ °C
- 3. Pulse test: Pulse Width \leq 300 μ s, duty cycle \leq 2%.
- 4. Switching time is essentially independent of operating temperature.

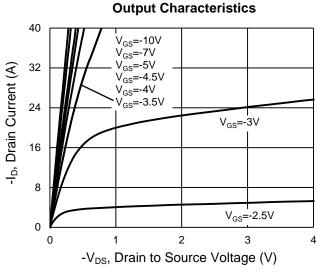
ORDERING INFORMATION

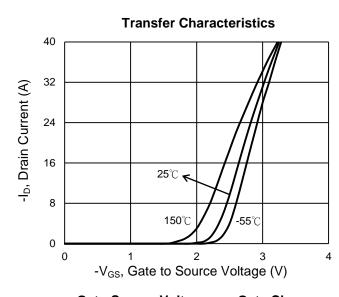
PART NO.	PACKAGE	PACKING
TSM085P03CS RLG	SOP-8	2,500pcs / 13" Reel

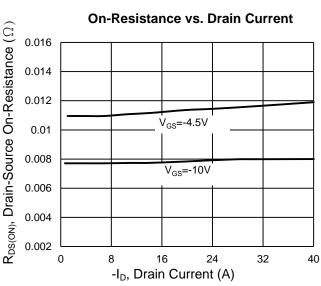


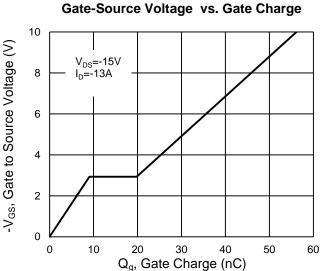
CHARACTERISTICS CURVES

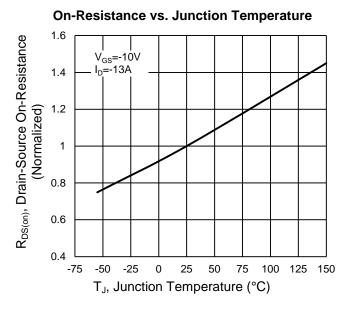
 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

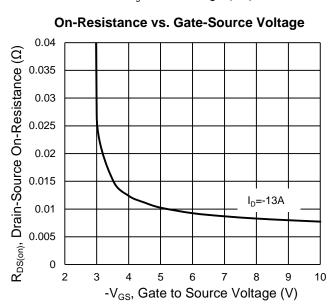










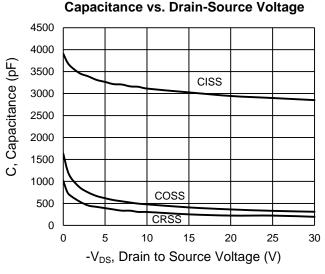


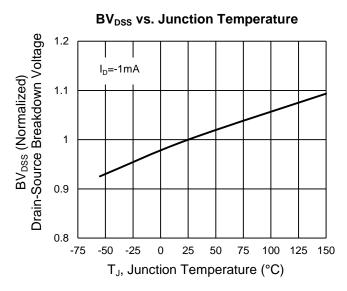
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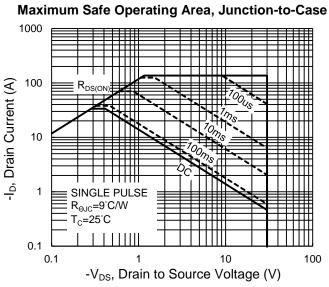


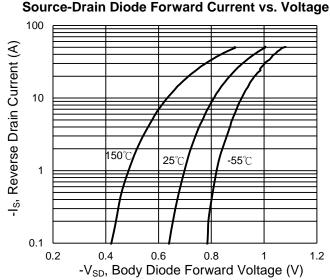
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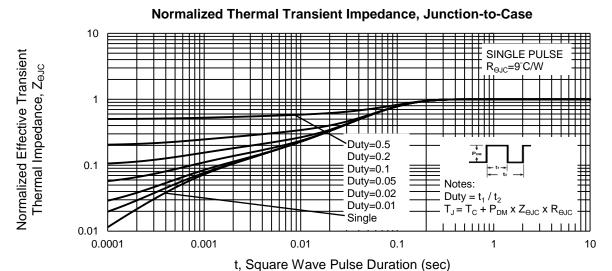
 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$











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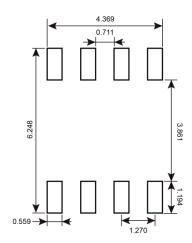




PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

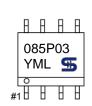
30P-8 4.85 ±0.15 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07 0.07

SUGGESTED PAD LAYOUT (Unit: Millimeters)



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MARKING DIAGRAM



Y = Year Code

M = Month Code

O =Jan P =Feb Q =Mar R =Apr

 $S = May \quad T = Jun \quad U = Jul \quad V = Aug$

 \mathbf{W} =Sep \mathbf{X} =Oct \mathbf{Y} =Nov \mathbf{Z} =Dec \mathbf{L} = Lot Code (1~9, A~Z)



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